

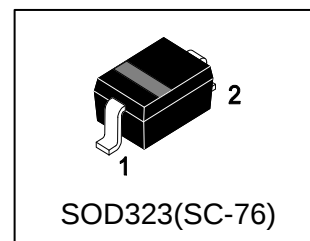
LUDZS15MBT1G

S-LUDZS15MBT1G

SURFACE MOUNT ZENER DIODE

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Steady state power rating of 400 mW
- Ideal for Surface Mount Application



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LUDZS15MBT1G	BW	3000/Tape&Reel

3. MAXIMUM RATINGS(Ta = 25°C)

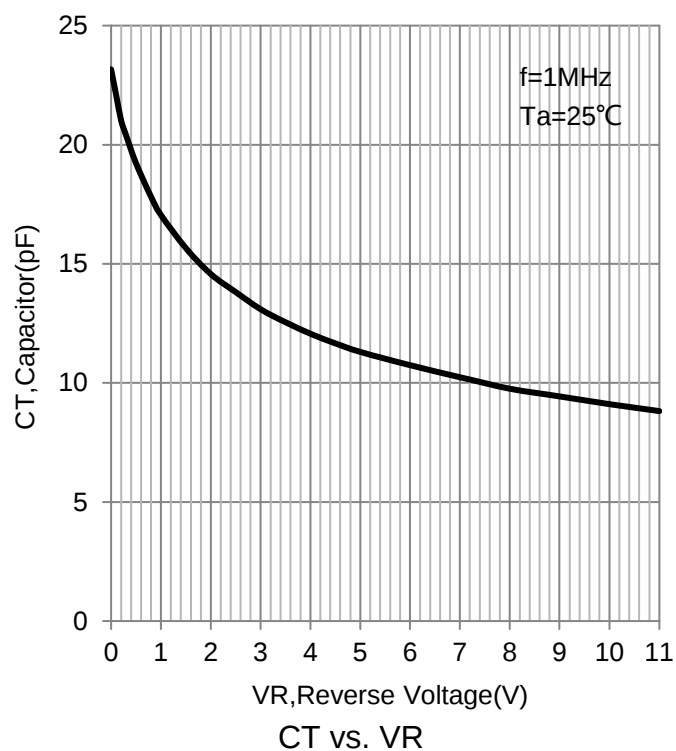
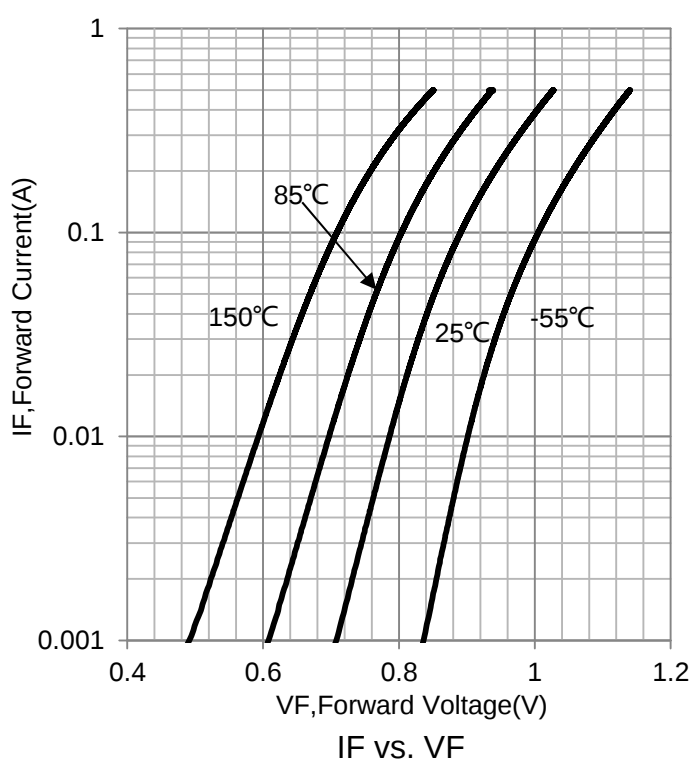
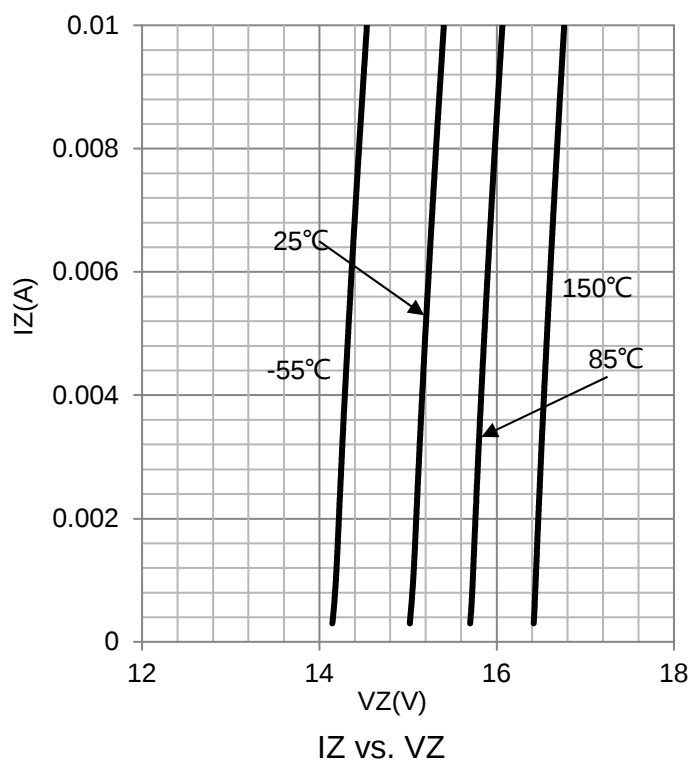
Parameter	Symbol	Limits	Unit
Total Device Dissipation, FR-5 Board (Note 1) @ TA = 25°C	PD	400	mW
Derate above 25°C		3.2	mW/°C
Thermal Resistance, Junction-to-Ambient(Note 1)	RθJA	312	°C/W
Junction and Storage temperature	TJ,Tstg	-55 ~ +150	°C

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Device	Zener voltage			Operating resistance		Rising operating resistance		Reverse current	
	VZ (V)			ZZ (Ohm)		Zzk (Ohm)		IR(μA)	
	Min.	Max.	IZ (mA)	Max.	IZ (mA)	Max.	IZ (mA)	Max.	VR (V)
LUDZS15MBT1G	14.700	15.300	5	30	5	110	1.0	0.1	11.0

1. FR-5 = 1.0×0.75×0.062 in.

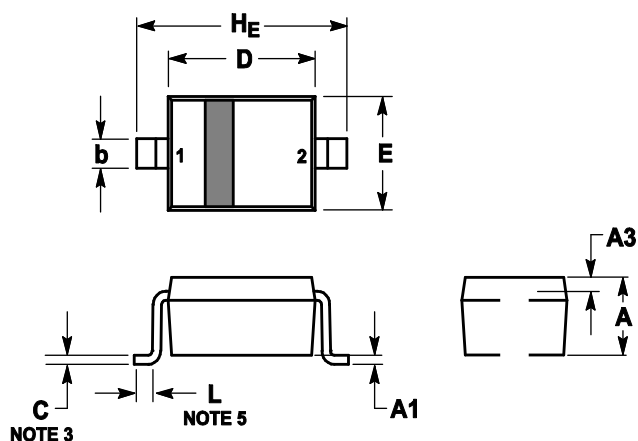
5.ELECTRICAL CHARACTERISTICS CURVES



6.OUTLINE AND DIMENSIONS

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H _E	2.3	2.5	2.7	0.09	0.098	0.105

7.SOLDERING FOOTPRINT

